

Electronic Patent Application Fee Transmittal

Application Number:	10715641			
Filing Date:	18-Nov-2003			
Title of Invention:	Raised solder-mask-defined (SMD) solder ball pads for a laminate electronic circuit board			
First Named Inventor/Applicant Name:	Tz-Cheng Chiu			
Filer:	Yingsheng Tung/Jackie McBride			
Attorney Docket Number:	TI-36052 (1962-07500)			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 3 months with \$0 paid	1253	1	1020	1020

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				1020